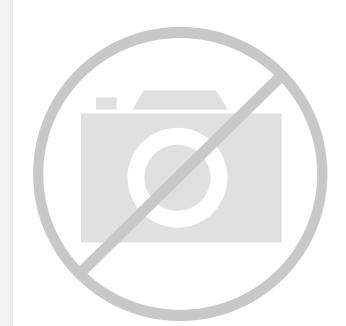
E·XFL



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	EBI/EMI, I ² C, IrDA, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	56
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K × 8
Voltage - Supply (Vcc/Vdd)	1.85V ~ 3.8V
Data Converters	A/D 8x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32g840f128-qfn64t

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

3.1.4 Direct Memory Access Controller (DMA)

The Direct Memory Access (DMA) controller performs memory operations independently of the CPU. This has the benefit of reducing the energy consumption and the workload of the CPU, and enables the system to stay in low energy modes when moving for instance data from the USART to RAM or from the External Bus Interface to a PWM-generating timer. The DMA controller uses the PL230 µDMA controller licensed from ARM.

3.1.5 Reset Management Unit (RMU)

The RMU is responsible for handling the reset functionality of the EFM32G.

3.1.6 Energy Management Unit (EMU)

The Energy Management Unit (EMU) manage all the low energy modes (EM) in EFM32G microcontrollers. Each energy mode manages if the CPU and the various peripherals are available. The EMU can also be used to turn off the power to unused SRAM blocks.

3.1.7 Clock Management Unit (CMU)

The Clock Management Unit (CMU) is responsible for controlling the oscillators and clocks on-board the EFM32G. The CMU provides the capability to turn on and off the clock on an individual basis to all peripheral modules in addition to enable/disable and configure the available oscillators. The high degree of flexibility enables software to minimize energy consumption in any specific application by not wasting power on peripherals and oscillators that are inactive.

3.1.8 Watchdog (WDOG)

The purpose of the watchdog timer is to generate a reset in case of a system failure, to increase application reliability. The failure may e.g. be caused by an external event, such as an ESD pulse, or by a software failure.

3.1.9 Peripheral Reflex System (PRS)

The Peripheral Reflex System (PRS) system is a network which lets the different peripheral module communicate directly with each other without involving the CPU. Peripheral modules which send out Reflex signals are called producers. The PRS routes these reflex signals to consumer peripherals which apply actions depending on the data received. The format for the Reflex signals is not given, but edge triggers and other functionality can be applied by the PRS.

3.1.10 External Bus Interface (EBI)

The External Bus Interface provides access to external parallel interface devices such as SRAM, FLASH, ADCs and LCDs. The interface is memory mapped into the address bus of the Cortex-M3. This enables seamless access from software without manually manipulating the IO settings each time a read or write is performed. The data and address lines are multiplexed in order to reduce the number of pins required to interface the external devices. The timing is adjustable to meet specifications of the external devices. The interface is limited to asynchronous devices.

3.1.11 Inter-Integrated Circuit Interface (I2C)

The I²C module provides an interface between the MCU and a serial I²C-bus. It is capable of acting as both a master and a slave, and supports multi-master buses. Both standard-mode, fast-mode and fastmode plus speeds are supported, allowing transmission rates all the way from 10 kbit/s up to 1 Mbit/s. Slave arbitration and timeouts are also provided to allow implementation of an SMBus compliant system. The interface provided to software by the I²C module, allows both fine-grained control of the transmission process and close to automatic transfers. Automatic recognition of slave addresses is provided in all energy modes.

3.1.12 Universal Synchronous/Asynchronous Receiver/Transmitter (USART)

The Universal Synchronous Asynchronous serial Receiver and Transmitter (USART) is a very flexible serial I/O module. It supports full duplex asynchronous UART communication as well as RS-485, SPI, MicroWire and 3-wire. It can also interface with ISO7816 Smart-Cards, and IrDA devices.

3.1.13 Pre-Programmed USB/UART Bootloader

The bootloader presented in application note AN0003 is pre-programmed in the device at factory. Autobaud and destructive write are supported. The autobaud feature, interface and commands are described further in the application note.

3.1.14 Universal Asynchronous Receiver/Transmitter (UART)

The Universal Asynchronous serial Receiver and Transmitter (UART) is a very flexible serial I/O module. It supports full- and half-duplex asynchronous UART communication.

3.1.15 Low Energy Universal Asynchronous Receiver/Transmitter (LEUART)

The unique LEUARTTM, the Low Energy UART, is a UART that allows two-way UART communication on a strict power budget. Only a 32.768 kHz clock is needed to allow UART communication up to 9600 baud/ s. The LEUART includes all necessary hardware support to make asynchronous serial communication possible with minimum of software intervention and energy consumption.

3.1.16 Timer/Counter (TIMER)

The 16-bit general purpose Timer has 3 compare/capture channels for input capture and compare/Pulse-Width Modulation (PWM) output. TIMER0 also includes a Dead-Time Insertion module suitable for motor control applications.

3.1.17 Real Time Counter (RTC)

The Real Time Counter (RTC) contains a 24-bit counter and is clocked either by a 32.768 kHz crystal oscillator, or a 32.768 kHz RC oscillator. In addition to energy modes EM0 and EM1, the RTC is also available in EM2. This makes it ideal for keeping track of time since the RTC is enabled in EM2 where most of the device is powered down.

3.1.18 Low Energy Timer (LETIMER)

The unique LETIMERTM, the Low Energy Timer, is a 16-bit timer that is available in energy mode EM2 in addition to EM1 and EM0. Because of this, it can be used for timing and output generation when most of the device is powered down, allowing simple tasks to be performed while the power consumption of the system is kept at an absolute minimum. The LETIMER can be used to output a variety of waveforms with minimal software intervention. It is also connected to the Real Time Counter (RTC), and can be configured to start counting on compare matches from the RTC.

3.1.19 Pulse Counter (PCNT)

The Pulse Counter (PCNT) can be used for counting pulses on a single input or to decode quadrature encoded inputs. It runs off either the internal LFACLK or the PCNTn_S0IN pin as external clock source. The module may operate in energy mode EM0 - EM3.

3.1.20 Analog Comparator (ACMP)

The Analog Comparator is used to compare the voltage of two analog inputs, with a digital output indicating which input voltage is higher. Inputs can either be one of the selectable internal references or from external pins. Response time and thereby also the current consumption can be configured by altering the current supply to the comparator.

3.1.21 Voltage Comparator (VCMP)

The Voltage Supply Comparator is used to monitor the supply voltage from software. An interrupt can be generated when the supply falls below or rises above a programmable threshold. Response time and thereby also the current consumption can be configured by altering the current supply to the comparator.

3.1.22 Analog to Digital Converter (ADC)

The ADC is a Successive Approximation Register (SAR) architecture, with a resolution of up to 12 bits at up to one million samples per second. The integrated input mux can select inputs from 8 external pins and 6 internal signals.

3.1.23 Digital to Analog Converter (DAC)

The Digital to Analog Converter (DAC) can convert a digital value to an analog output voltage. The DAC is fully differential rail-to-rail, with 12-bit resolution. It has two single-ended output buffers which can be combined into one differential output. The DAC may be used for a number of different applications such as sensor interfaces or sound output.

3.2.9 EFM32G842

The features of the EFM32G842 is a subset of the feature set described in the EFM32G Reference Manual. The following table describes device specific implementation of the features.

Module	Configuration	Pin Connections				
Cortex-M3	Full configuration	NA				
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO, DBG_SWO				
MSC	Full configuration	NA				
DMA	Full configuration	NA				
RMU	Full configuration	NA				
EMU	Full configuration	NA				
СМU	Full configuration	CMU_OUT0, CMU_OUT1				
WDOG	Full configuration	NA				
PRS	Full configuration	NA				
I2C0	Full configuration	I2C0_SDA, I2C0_SCL				
USART0	Full configuration with IrDA	US0_TX, US0_RX. US0_CLK, US0_CS				
USART1	Full configuration	US1_TX, US1_RX, US1_CLK, US1_CS				
USART2	Full configuration	US2_TX, US2_RX, US2_CLK, US2_CS				
LEUART0	Full configuration	LEU0_TX, LEU0_RX				
LEUART1	Full configuration	LEU1_TX, LEU1_RX				
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]				
TIMER1	Full configuration	TIM1_CC[2:0]				
TIMER2	Full configuration	TIM2_CC[2:0]				
RTC	Full configuration	NA				
LETIMER0	Full configuration	LET0_O[1:0]				
PCNT0	Full configuration, 8-bit count register	PCNT0_S[1:0]				
PCNT1	Full configuration, 8-bit count register	PCNT1_S[1:0]				
PCNT2	Full configuration, 8-bit count register	PCNT2_S[1:0]				
ACMP0	Full configuration	ACMP0_CH[3:0], ACMP0_O				
ACMP1	Full configuration	ACMP1_CH[7:4], ACMP1_O				
VCMP	Full configuration	NA				
ADC0	Full configuration	ADC0_CH[7:0]				
DAC0	Full configuration	DAC0_OUT[0]				
AES	Full configuration	NA				
GPIO	53 pins	Available pins are shown in Table 4.3 (p. 57)				

Table 3.9. EFM32G842 Configuration Summary

EFM32G Data Sheet System Overview

_		
0x400e0400	AES	0xffffffe
0x400e0000	AES	0xe0100000
0x400cc400	PRS	0xe00ffff
0x400cc000	FRS	CM3 Peripherals
0x400ca400	RMU	0xe0000000
0x400ca000	NH0	0xdfffffff
0x400c8400	СМИ	0.Aditititi
0x400c8000	6110	0×90000000
0x400c6400	EMU	0x8fffffff
0x400c6000		EBI Region 3
0x400c4000 0x400c2000	DMA	0×8c000000
0x400c2000		0x8bfffff
0x400c0400	MSC	EBI Region 2
0x4008a400		0×88000000
0x4008a000	LCD	0x87fffff
0x40088400		EBI Region 1
0x40088000	WDOG	0×84000000
0x40086c00	DONTO	0x83ffffff
0x40086800	PCNT2	EBI Region 0 0x80000000
0x40086400	PCNT1 PCNT0	
0x40086000	PCNTU	0x7fffffff
0x40084800	LEUART1	0×44000000
0x40084400	LEUARTO	0x43ffffff
0x40084000	LEGATIO	Peripherals (bit-band)
0x40082400	LETIMERO	0×42000000
0×40082000		0x41ffffff
0x40080400	RTC	
0×40080000		0×41000000
0x40010c00	TIMER2	0x40ffffff
0×40010800 0×40010400	TIMER1	Peripherals
0x40010400	TIMERO	0×40000000
0x4000e400		0x3ffffff
0x4000e000	UART0	
0x4000cc00		0×22200000
0x4000c800	USART2	0x221fffff
0x4000c400	USART1	SRAM (bit-band)
0x4000c000	USART0	0×22000000
0x4000a400	2C0	/ 0x21ffffff
0x4000a000	1200	0×20004000
0x40008400	EBI	CDAM (1C Hp) 0x20003fff
0x40008000	LDI	SRAM (16 KB)
0x40007000	GPIO	(data space) 0x20000000
0x40006000	GHO	0x1fffffff
0x40004400	DACO	
0x40004000		
0x40002400	ADC0	
0x40002000		/ Code
0×40001800 0×40001400	ACMP1	
0x40001400	ACMP0	
0x40001000		
0x40000400	VCMP	/ 0×0000000

Figure 3.3. System Address Space with Peripheral Listing

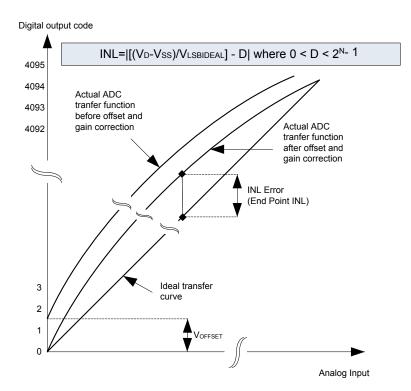


Figure 4.27. Integral Non-Linearity (INL)

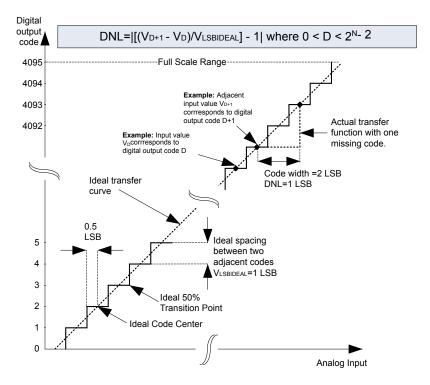


Figure 4.28. Differential Non-Linearity (DNL)

4.11 Digital Analog Converter (DAC)

Table 4.15. DAC

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Output voltage range	M	VDD voltage reference, single- ended	0	_	V _{DD}	V
Output voltage range	V _{DACOUT}	VDD voltage reference, differen- tial	-V _{DD}	_	V _{DD}	V
Output common mode voltage range	V _{DACCM}		0	—	V _{DD}	V
		500 kSamples/s, 12 bit, internal 1.25 V reference, Continuous Mode	_	400 ¹	650 ¹	μA
Average active current	I _{DAC}	100 kSamples/s, 12 bit, internal 1.25 V reference, Sample/Hold Mode	—	200 ¹	250 ¹	μΑ
		1 kSamples/s 12 bit, internal 1.25 V reference, Sample/Off Mode	—	17 ¹	25 ¹	μΑ
Sample rate	SR _{DAC}		—	—	500	ksamples/s
		Continuous Mode		—	1000	kHz
DAC clock frequency	f _{DAC}	Sample/Hold Mode	_	—	250	kHz
		Sample/Off Mode		—	250	kHz
Clock cycles per conversion	CYC _{DACCONV}		—	2	_	cycles
Conversion time	t _{DACCONV}		2	—	_	μs
Settling time	t _{DACSETTLE}		_	5	_	μs
		500 kSamples/s, 12 bit, single- ended, internal 1.25 V reference	_	58	_	dB
		500 kSamples/s, 12 bit, single- ended, internal 2.5 V reference	—	59	-	dB
Signal-to-Noise Ratio (SNR)	SNR _{DAC}	500 kSamples/s, 12 bit, differen- tial, internal 1.25 V reference	—	58	-	dB
		500 kSamples/s, 12 bit, differen- tial, internal 2.5 V reference	—	58	-	dB
		500 kSamples/s, 12 bit, differential, V_{DD} reference	—	59	_	dB

5.1.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32G200 and EFM32G210 is shown in the following table. Each GPIO port is organized as 16bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	_	_	_	_	_	_	_	_	_	_	_	_	_	PA2	PA1	PA0
Port B	_	PB14	PB13	_	PB11	_	_	PB8	PB7	—	_	_		_	_	_
Port C	PC15	PC14	PC13	_	—	_	—	—	—	—	—	—		_	PC1	PC0
Port D	_	_	_	_	_	_	_	_	PD7	PD6	PD5	PD4		_	—	_
Port E	_	_	PE13	PE12	PE11	PE10	_	_		_	_		_	_		_
Port F	_	_			_		_	_	_	—	—	_		PF2	PF1	PF0

Table 5.3. GPIO Pinout

5.3 EFM32G230 (QFN64)

5.3.1 Pinout

The EFM32G230 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

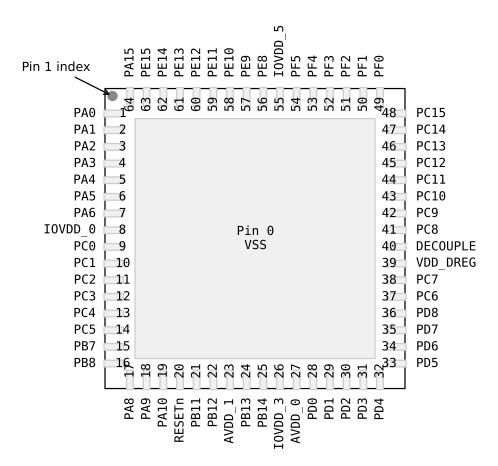


Figure 5.3. EFM32G230 Pinout (top view, not to scale)

Table 5.7. Device Pinout

QFN64 P	in# and Name		Pin Alternate	e Functionality / Description				
Pin #	Pin Name	Analog	Timers	Communication	Other			
0	VSS	Ground.						
1	PA0		TIM0_CC0 #0/1	I2C0_SDA #0				
2	PA1		TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0			
3	PA2		TIM0_CC2 #0/1		CMU_CLK0 #0			
4	PA3		TIM0_CDTI0 #0					
5	PA4		TIM0_CDTI1 #0					

	P100 Pin# d Name		Ρ	in Alternate Functionality	/ / Description	
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
6	PA5		EBI_AD14 #0	TIM0_CDTI2 #0	LEU1_TX #1	
7	PA6		EBI_AD15 #0		LEU1_RX #1	
8	IOVDD_0	Digital IO pov	wer supply 0.			
9	PB0			TIM1_CC0 #2		
10	PB1			TIM1_CC1 #2		
11	PB2			TIM1_CC2 #2		
12	PB3			PCNT1_S0IN #1	US2_TX #1	
13	PB4			PCNT1_S1IN #1	US2_RX #1	
14	PB5				US2_CLK #1	
15	PB6				US2_CS #1	
16	VSS	Ground.		1	1	
17	IOVDD_1	Digital IO pov	wer supply 1.			
18	PC0	ACMP0_C H0		PCNT0_S0IN #2	US1_TX #0	
19	PC1	ACMP0_C H1		PCNT0_S1IN #2	US1_RX #0	
20	PC2	ACMP0_C H2			US2_TX #0	
21	PC3	ACMP0_C H3			US2_RX #0	
22	PC4	ACMP0_C H4		LETIM0_OUT0 #3 PCNT1_S0IN #0	US2_CLK #0	
23	PC5	ACMP0_C H5		LETIM0_OUT1 #3 PCNT1_S1IN #0	US2_CS #0	
24	PB7	LFXTAL_P			US1_CLK #0	
25	PB8	LFXTAL_N			US1_CS #0	
26	PA7					
27	PA8			TIM2_CC0 #0		
28	PA9			TIM2_CC1 #0		
29	PA10			TIM2_CC2 #0		
30	PA11					
31	IOVDD_2	Digital IO pov	wer supply 2.			
32	VSS	Ground.				
33	PA12			TIM2_CC0 #1		
34	PA13			TIM2_CC1 #1		
35	PA14			TIM2_CC2 #1		
36	RESETn			external reset source to this ure that reset is released.	pin, it is required to only c	Irive this pin low during

	P100 Pin# d Name	Pin Alternate Functionality / Description									
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other					
92	PE8		EBI_AD00 #0	PCNT2_S0IN #1							
93	PE9		EBI_AD01 #0	PCNT2_S1IN #1							
94	PE10		EBI_AD02 #0	TIM1_CC0 #1	US0_TX #0	BOOT_TX					
95	PE11		EBI_AD03 #0	TIM1_CC1 #1	US0_RX #0	BOOT_RX					
96	PE12		EBI_AD04 #0	TIM1_CC2 #1	US0_CLK #0						
97	PE13		EBI_AD05 #0		US0_CS #0	ACMP0_O #0					
98	PE14		EBI_AD06 #0		LEU0_TX #2						
99	PE15		EBI_AD07 #0		LEU0_RX #2						
100	PA15		EBI_AD08 #0								

Alternate					LOCATION
Functionality	0	1	2	3	Description
TIM2_CC0	PA8	PA12	PC8		Timer 2 Capture Compare input / output channel 0.
TIM2_CC1	PA9	PA13	PC9		Timer 2 Capture Compare input / output channel 1.
TIM2_CC2	PA10	PA14	PC10		Timer 2 Capture Compare input / output channel 2.
U0_RX	PF7	PE1	PA4	PC15	UART0 Receive input.
U0_TX	PF6	PE0	PA3	PC14	UART0 Transmit output. Also used as receive input in half duplex communication.
US0_CLK	PE12	PE5	PC9		USART0 clock input / output.
US0_CS	PE13	PE4	PC8		USART0 chip select input / output.
					USART0 Asynchronous Receive.
US0_RX	PE11	PE6	PC10		USART0 Synchronous mode Master Input / Slave Output (MI-SO).
		DET	5044		USART0 Asynchronous Transmit.Also used as receive input in half duplex communication.
US0_TX	PE10	PE7	PC11		USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7	PD2			USART1 clock input / output.
US1_CS	PB8	PD3			USART1 chip select input / output.
					USART1 Asynchronous Receive.
US1_RX	PC1	PD1			USART1 Synchronous mode Master Input / Slave Output (MI-SO).
	DOG				USART1 Asynchronous Transmit.Also used as receive input in half duplex communication.
US1_TX	PC0	PD0			USART1 Synchronous mode Master Output / Slave Input (MOSI).
US2_CLK	PC4	PB5			USART2 clock input / output.
US2_CS	PC5	PB6			USART2 chip select input / output.
					USART2 Asynchronous Receive.
US2_RX	PC3	PB4			USART2 Synchronous mode Master Input / Slave Output (MI-SO).
	DC2				USART2 Asynchronous Transmit.Also used as receive input in half duplex communication.
US2_TX	PC2	PB3			USART2 Synchronous mode Master Output / Slave Input (MOSI).

5.6.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Alternate					LOCATION
Functionality	0	1	2	3	Description
ACMP0_CH0	PC0				Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1				Analog comparator ACMP0, channel 1.
ACMP0_CH2	PC2				Analog comparator ACMP0, channel 2.
ACMP0_CH3	PC3				Analog comparator ACMP0, channel 3.
ACMP0_CH4	PC4				Analog comparator ACMP0, channel 4.
ACMP0_CH5	PC5				Analog comparator ACMP0, channel 5.
ACMP0_CH6	PC6				Analog comparator ACMP0, channel 6.
ACMP0_CH7	PC7				Analog comparator ACMP0, channel 7.
ACMP0_O	PE13	PE2			Analog comparator ACMP0, digital output.
ACMP1_CH0	PC8				Analog comparator ACMP1, channel 0.
ACMP1_CH1	PC9				Analog comparator ACMP1, channel 1.
ACMP1_CH2	PC10				Analog comparator ACMP1, channel 2.
ACMP1_CH3	PC11				Analog comparator ACMP1, channel 3.
ACMP1_CH4	PC12				Analog comparator ACMP1, channel 4.
ACMP1_CH5	PC13				Analog comparator ACMP1, channel 5.
ACMP1_CH6	PC14				Analog comparator ACMP1, channel 6.
ACMP1_CH7	PC15				Analog comparator ACMP1, channel 7.
ACMP1_O	PF2	PE3			Analog comparator ACMP1, digital output.
ADC0_CH0	PD0				Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PD1				Analog to digital converter ADC0, input channel number 1.
ADC0_CH2	PD2				Analog to digital converter ADC0, input channel number 2.
ADC0_CH3	PD3				Analog to digital converter ADC0, input channel number 3.
ADC0_CH4	PD4				Analog to digital converter ADC0, input channel number 4.
ADC0_CH5	PD5				Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6				Analog to digital converter ADC0, input channel number 6.
ADC0_CH7	PD7				Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PE11				Bootloader RX.
BOOT_TX	PE10				Bootloader TX.
CMU_CLK0	PA2	PC12			Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8			Clock Management Unit, clock output number 1.

Table 5.17. Alternate functionality overview

5.9.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Alternate					LOCATION
Functionality	0	1	2	3	Description
ACMP0_CH0	PC0				Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1				Analog comparator ACMP0, channel 1.
ACMP0_CH2	PC2				Analog comparator ACMP0, channel 2.
ACMP0_CH3	PC3				Analog comparator ACMP0, channel 3.
ACMP0_CH4	PC4				Analog comparator ACMP0, channel 4.
ACMP0_CH5	PC5				Analog comparator ACMP0, channel 5.
ACMP0_CH6	PC6				Analog comparator ACMP0, channel 6.
ACMP0_CH7	PC7				Analog comparator ACMP0, channel 7.
ACMP0_O	PE13	PE2			Analog comparator ACMP0, digital output.
ACMP1_CH0	PC8				Analog comparator ACMP1, channel 0.
ACMP1_CH1	PC9				Analog comparator ACMP1, channel 1.
ACMP1_CH2	PC10				Analog comparator ACMP1, channel 2.
ACMP1_CH3	PC11				Analog comparator ACMP1, channel 3.
ACMP1_CH4	PC12				Analog comparator ACMP1, channel 4.
ACMP1_CH5	PC13				Analog comparator ACMP1, channel 5.
ACMP1_CH6	PC14				Analog comparator ACMP1, channel 6.
ACMP1_CH7	PC15				Analog comparator ACMP1, channel 7.
ACMP1_O	PF2	PE3			Analog comparator ACMP1, digital output.
ADC0_CH0	PD0				Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PD1				Analog to digital converter ADC0, input channel number 1.
ADC0_CH2	PD2				Analog to digital converter ADC0, input channel number 2.
ADC0_CH3	PD3				Analog to digital converter ADC0, input channel number 3.
ADC0_CH4	PD4				Analog to digital converter ADC0, input channel number 4.
ADC0_CH5	PD5				Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6				Analog to digital converter ADC0, input channel number 6.
ADC0_CH7	PD7				Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PE11				Bootloader RX.
BOOT_TX	PE10				Bootloader TX.
CMU_CLK0	PA2	PC12			Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8			Clock Management Unit, clock output number 1.

Table 5.26. Alternate functionality overview

Alternate					LOCATION
Functionality	0	1	2	3	Description
DAC0_OUT0	PB11				Digital to Analog Converter DAC0 output channel number 0.
DAC0_OUT1	PB12				Digital to Analog Converter DAC0 output channel number 1.
					Debug-interface Serial Wire clock input.
DBG_SWCLK	PF0	PF0			Note that this function is enabled to pin out of reset, and has a built-in pull down.
					Debug-interface Serial Wire data input / output.
DBG_SWDIO	PF1	PF1			Note that this function is enabled to pin out of reset, and has a built-in pull up.
					Debug-interface Serial Wire viewer Output.
DBG_SWO	PF2	PC15			Note that this function is not enabled after reset, and must be enabled by software to be used.
EBI_AD00	PE8				External Bus Interface (EBI) address and data input / output pin 00.
EBI_AD01	PE9				External Bus Interface (EBI) address and data input / output pin 01.
EBI_AD02	PE10				External Bus Interface (EBI) address and data input / output pin 02.
EBI_AD03	PE11				External Bus Interface (EBI) address and data input / output pin 03.
EBI_AD04	PE12				External Bus Interface (EBI) address and data input / output pin 04.
EBI_AD05	PE13				External Bus Interface (EBI) address and data input / output pin 05.
EBI_AD06	PE14				External Bus Interface (EBI) address and data input / output pin 06.
EBI_AD07	PE15				External Bus Interface (EBI) address and data input / output pin 07.
EBI_AD08	PA15				External Bus Interface (EBI) address and data input / output pin 08.
EBI_AD09	PA0				External Bus Interface (EBI) address and data input / output pin 09.
EBI_AD10	PA1				External Bus Interface (EBI) address and data input / output pin 10.
EBI_AD11	PA2				External Bus Interface (EBI) address and data input / output pin 11.
EBI_AD12	PA3				External Bus Interface (EBI) address and data input / output pin 12.
EBI_AD13	PA4				External Bus Interface (EBI) address and data input / output pin 13.
EBI_AD14	PA5				External Bus Interface (EBI) address and data input / output pin 14.
EBI_AD15	PA6				External Bus Interface (EBI) address and data input / output pin 15.
EBI_ALE	PF3				External Bus Interface (EBI) Address Latch Enable output.

Alternate					LOCATION
Functionality	0	1	2	3	Description
LCD_SEG30	PD11				LCD segment line 30. Segments 28, 29, 30 and 31 are con- trolled by SEGEN7.
LCD_SEG31	PD12				LCD segment line 31. Segments 28, 29, 30 and 31 are con- trolled by SEGEN7.
LCD_SEG32	PB0				LCD segment line 32. Segments 32, 33, 34 and 35 are con- trolled by SEGEN8.
LCD_SEG33	PB1				LCD segment line 33. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG34	PB2				LCD segment line 34. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG35	PA7				LCD segment line 35. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG36	PA8				LCD segment line 36. Segments 36, 37, 38 and 39 are con- trolled by SEGEN9.
LCD_SEG37	PA9				LCD segment line 37. Segments 36, 37, 38 and 39 are con- trolled by SEGEN9.
LCD_SEG38	PA10				LCD segment line 38. Segments 36, 37, 38 and 39 are con- trolled by SEGEN9.
LCD_SEG39	PA11				LCD segment line 39. Segments 36, 37, 38 and 39 are con- trolled by SEGEN9.
LETIM0_OUT0	PD6	PB11	PF0	PC4	Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7	PB12	PF1	PC5	Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15		LEUART0 Receive input.
LEU0_TX	PD4	PB13	PE14		LEUART0 Transmit output. Also used as receive input in half duplex communication.
LEU1_RX	PC7	PA6			LEUART1 Receive input.
LEU1_TX	PC6	PA5			LEUART1 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8				Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7				Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	PC13	PE0	PC0		Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14	PE1	PC1		Pulse Counter PCNT0 input number 1.
PCNT1_S0IN	PC4	PB3			Pulse Counter PCNT1 input number 0.
PCNT1_S1IN	PC5	PB4			Pulse Counter PCNT1 input number 1.
PCNT2_S0IN	PD0	PE8			Pulse Counter PCNT2 input number 0.
PCNT2_S1IN	PD1	PE9			Pulse Counter PCNT2 input number 1.
TIM0_CC0	PA0	PA0	PF6	PD1	Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1	PF7	PD2	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2	PF8	PD3	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0	PA3	PC13	PF3	PC13	Timer 0 Complimentary Deat Time Insertion channel 0.

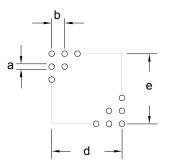


Figure 6.4. BGA112 PCB Stencil Design

Table 6.3. BGA112 PCB Stencil Design Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
а	0.33
b	0.80
d	8.00
е	8.00

Note:

1. The drawings are not to scale.

2. All dimensions are in millimeters.

3. All drawings are subject to change without notice.

4. The PCB Land Pattern drawing is in compliance with IPC-7351B.

5. Stencil thickness 0.125 mm.

6. For detailed pin-positioning, see Pin Definitions.

13.2 Revision 2.00

May 10th, 2017

Consolidated all EFM32G data sheets:

- EFM32G200
- EFM32G210
- EFM32G222
- EFM32G230
- EFM32G232
- EFM32G280
- EFM32G290
- EFM32G840
- EFM32G842
- EFM32G880
- EFM32G890

New formatting throughout.

Added 1. Feature List.

Updated ordering codes in 2. Ordering Information for Revision E and tape and reel.

Added Figure 2.1 Ordering Code Decoder on page 5.

Separated Memory Map figure into Figure 3.2 System Address Space with Core and Code Space Listing on page 27 and Figure 3.3 System Address Space with Peripheral Listing on page 28 for readability.

Removed footnote for storage temperature range in 4.2 Absolute Maximum Ratings.

In 4.6 Power Management:

- Updated EM0 condition for V_{BODextthr-} specification.
- Added V_{BODextthr-} in EM1 and EM2 specifications.
- Updated EM0 condition for V_{BODextthr+} specification.

Updated Flash page erase time and device erase time in 4.7 Flash and added footnotes.

Updated figures in 4.9.3 LFRCO.

Updated figures and HFRCO current consumption typical values in 4.9.4 HFRCO.

In 4.10 Analog Digital Converter (ADC):

- · Updated test conditions, updated specifications, and added footnote for average active current.
- Added input bias current.
- · Added input offset current.
- · Updated ADC clock frequency.
- Updated SNR, SINAD and SFDR.
- Updated offset voltage.
- Updated missing codes.
- · Added gain error drift and offset error drift.
- Added VREF output voltage, VREF voltage drift, VREF temperature drift, VREF current consumption, and ADC and DAC VREF matching.

In 4.11 Digital Analog Converter (DAC):

- Updated I_{DAC} parameter, test conditions, and footnote.
- Added DAC load current specification to 4.11 Digital Analog Converter (DAC).
- Added VREF output voltage, VREF voltage drift, VREF temperature drift, VREF current consumption, and ADC and DAC VREF matching.

Updated ACMP active current (BIASPROG=0b1111, FULLBIAS=1 and HALFBIAS=0 in ACMPn_CTRL register) typical value in 4.12 Analog Comparator (ACMP).

Updated VCMP hysteresis typical value in 4.13 Voltage Comparator (VCMP).

13.9 Revision 1.40

February 27th, 2012

Updated Power Management section.

Corrected operating voltage from 1.8 V to 1.85 V.

Corrected TGRAD_{ADCTH} parameter.

Corrected package drawing.

Updated PCB land pattern, solder mask and stencil design.

For LQFP48 devices, corrected available Pulse Counters from 3 to 2.

For LQFP48 devices, corrected available LEUARTs from 2 to 1.

For LQFP64 devices, corrected ordering codes in the ordering information table.

13.10 Revision 1.30

May 20th, 2011

This revision applies the following devices:

- EFM32G200
- EFM32G210
- EFM32G230
- EFM32G280
- EFM32G290
- EFM32G840
- EFM32G880
- EFM32G890

Updated LFXO load capacitance section.

13.11 Revision 1.20

December 17th, 2010

This revision applies the following devices:

- EFM32G200
- EFM32G210
- EFM32G230
- EFM32G280
- EFM32G290
- EFM32G840
- EFM32G880
- EFM32G890

Increased max storage temperature.

Added data for <150°C and <70°C on Flash data retention.

Changed latch-up sensitivity test description.

Added IO leakage current.

For LQFP100 devices, updated ESD CDM value.

Added Flash current consumption.

Updated HFRCO data.

Updated LFRCO data.

Added graph for ADC Absolute Offset over temperature.

Added graph for ADC Temperature sensor readout.

13.12 Revision 1.11

November 17th, 2010

This revision applies the following devices:

- EFM32G200
- EFM32G210
- EFM32G230
- EFM32G280
- EFM32G290
- EFM32G840
- EFM32G880
- EFM32G890

Corrected maximum DAC clock speed for continuous mode.

Added DAC sample-hold mode voltage drift rate.

Added pulse widths detected by the HFXO glitch detector.

Added power sequencing information to Power Management section.





Simplicity Studio

One-click access to MCU and wireless tools, documentation, software, source code libraries & more. Available for Windows, Mac and Linux!







Support and Community community.silabs.com

Disclaimer

Silicon Labs intends to provide customers with the latest, accurate, and in-depth documentation of all peripherals and modules available for system and software implementers using or intending to use the Silicon Labs products. Characterization data, available modules and peripherals, memory sizes and memory addresses refer to each specific device, and "Typical" parameters provided can and do vary in different applications. Application examples described herein are for illustrative purposes only. Silicon Labs reserves the right to make changes without further notice and limitation to product information, specifications, and descriptions herein, and does not give warranties as to the accuracy or completeness of the included information. Silicon Labs shall have no liability for the consequences of use of the information supplied herein. This document does not imply or express copyright licenses granted hereunder to design or fabricate any integrated circuits. The products are not designed or authorized to be used within any Life Support System without the specific written consent of Silicon Labs. A "Life Support System" is any product or system intended to support or sustain life and/or health, which, if it fails, can be reasonably expected to result in significant personal injury or death. Silicon Labs products are not designed or authorized for military applications. Silicon Labs products shall under no circumstances be used in weapons of mass destruction including (but not limited to) nuclear, biological or chemical weapons, or missiles capable of delivering such weapons.

Trademark Information

Silicon Laboratories Inc.®, Silicon Laboratories®, Silicon Labs®, SiLabs® and the Silicon Labs logo®, Bluegiga®, Bluegiga Logo®, Clockbuilder®, CMEMS®, DSPLL®, EFM®, EFM32®, EFR, Ember®, Energy Micro, Energy Micro logo and combinations thereof, "the world's most energy friendly microcontrollers", Ember®, EZLink®, EZRadio®, EZRadioPRO®, Gecko®, ISOmodem®, Micrium, Precision32®, ProSLIC®, Simplicity Studio®, SiPHY®, Telegesis, the Telegesis Logo®, USBXpress®, Zentri and others are trademarks or registered trademarks of Silicon Labs. ARM, CORTEX, Cortex-M3 and THUMB are trademarks or registered trademarks of ARM Holdings. Keil is a registered trademark of ARM Limited. All other products or brand names mentioned herein are trademarks of their respective holders.



Silicon Laboratories Inc. 400 West Cesar Chavez Austin, TX 78701 USA

http://www.silabs.com